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APPLICANT : TOAGOSEI CO LTD;

INVENTOR : WASHIMI AKIRA;

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TITLE : CURATIVE COMPOSITION

ABSTRACT : PROBLEM TO BE SOLVED: To provide curative compositions which can form cured products excellent in heat resistance and solvent resistance and can suitably be used as adhesives, adhesive tapes and the like.

SOLUTION: This curative composition comprises (A) an alkenylphenol compound, (B) a maleimide compound, and (C) a linear chain or branched chain silicone having one or more (meth)acryloyl groups in the molecule at a ratio of component (A) to component (B) of 20-80 wt. %:80-20 wt. % with a ratio of component (C), based on the total amount of components (A), (B) and (C), of 10-70 wt. %.

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